New Composite Bonding Adhesive from Huntsman Advanced Materials

Epibond® 100 A/B is a two-component, heat-curing epoxy structural adhesive designed for demanding applications requiring high hot / wet Tg performance, and elevated temperature performance. Easy to mix and apply, Epibond® 100 A/B bonds composites and dissimilar substrates such as carbon fiber, glass reinforced composite, PEEK and aluminum. Available in dual syringe 50 ML and 200 ML cartridges for easy use. Does not intentionally contain any Substances of Very High Concern (SVHC) as defined under REACH.

**Key Features**
- 2:1 (pbv) mix ratio
- Thixotropic paste with spacer beads
- 100-120 minutes working time
- Moderate heat cure cycle
- Service temperatures up to 300° F
- High Tg, lap shear strength

**Key Benefits**
- Easy to process by hand or cartridge
- Gap filling allows versatile use with uniform bond line
- Long working time allows for large composite part assembly
- Variable handling strengths
- Retention of properties under demanding hot / wet conditions

Contact your sales representative or distributor for a sample today.

Epibond® is a registered trademark of Huntsman Corporation or an affiliate thereof in one or more, but not all countries.